

[What Is Claimed Is]

1. A film-forming apparatus characterized by having means for irradiating a component provided in a film-forming chamber with at least one selected from the group consisting of infrared light, UV-light, and visible light.
- 5      2. A film-forming apparatus characterized by having a lamp light source for irradiating a component provided in a film-forming chamber with at least one selected from the group consisting of infrared light, UV-light, and visible light.
3. A film-forming apparatus according to claim 2, characterized in that the lamp light source is in a rectangular or oblong shape.
- 10      4. A film-forming apparatus characterized by having means for heating a component provided in a film-forming chamber with radiation heat.
5. A film-forming apparatus, characterized in that a component provided in a film-forming chamber is equipped with a conductor for heating the component with radiation heat.
- 15      6. A film-forming apparatus according to claim 1, characterized in that the component is an adhesion preventing shield.
7. A film-forming apparatus according to claim 1, characterized in that an exhaust treatment chamber is connected to the film-forming chamber.

8. A film-forming apparatus according to claim 7, characterized in that plasma is generated in the exhaust treatment chamber.

9. A method of cleaning a film-forming apparatus, comprising the steps of:  
irradiating a component provided in a film-forming chamber with at least one  
5 selected from the group consisting of infrared light, UV-light, and visible light,  
thereby sublimating a vapor-deposition material adhering to the component; and  
exhausting the sublimated evaporation material.

10. A method of cleaning according to claim 9, characterized in that at least  
one selected from the group consisting of the infrared light, UV-light, and visible  
10 light is radiated by using a lamp light source provided in the film-forming chamber.

11. A method of cleaning according to claim 9, characterized in that an  
irradiation surface of at least one selected from the group consisting of the infrared  
light, UV-light, and visible light is in a rectangular or oblong shape.

12. A method of cleaning according to claim 9, characterized in that, in the  
15 sublimation step, gas containing a halogen-group element is flowed in the film-  
forming chamber.

13. A method of cleaning according to claim 9, characterized in that the  
sublimated vapor-deposition material is exposed to plasma during exhaust.

14. A method of cleaning according to claim 13, characterized in that the

plasma is oxygen plasma.

15. A method of cleaning according to claim 9, characterized in that the vapor-deposition material is an organic EL material.

5 SUB B1 16. A method of manufacturing an electro-optical device including the method of cleaning of claim 9.

17. A method of manufacturing an electro-optical device including the method of cleaning of claim 9.

18. A film-forming apparatus according to claim 2, characterized in that the component is an adhesion preventing shield.

10 19. A film-forming apparatus according to claim 2, characterized in that an exhaust treatment chamber is connected to the film-forming chamber.

20. A film-forming apparatus according to claim 19, characterized in that plasma is generated in the exhaust treatment chamber.

15 21. A film-forming apparatus according to claim 4, characterized in that the component is an adhesion preventing shield.

22. A film-forming apparatus according to claim 4, characterized in that an exhaust treatment chamber is connected to the film-forming chamber.

23. A film-forming apparatus according to claim 22, characterized in that plasma is generated in the exhaust treatment chamber.

24. A film-forming apparatus according to claim 5, characterized in that the component is an adhesion preventing shield.

5 25. A film-forming apparatus according to claim 5, characterized in that an exhaust treatment chamber is connected to the film-forming chamber.

26. A film-forming apparatus according to claim 25, characterized in that plasma is generated in the exhaust treatment chamber.

add b2